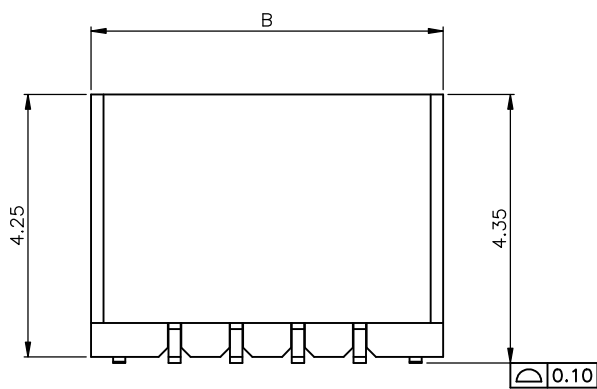
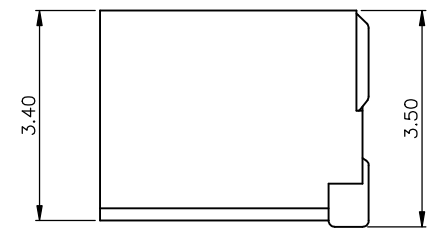
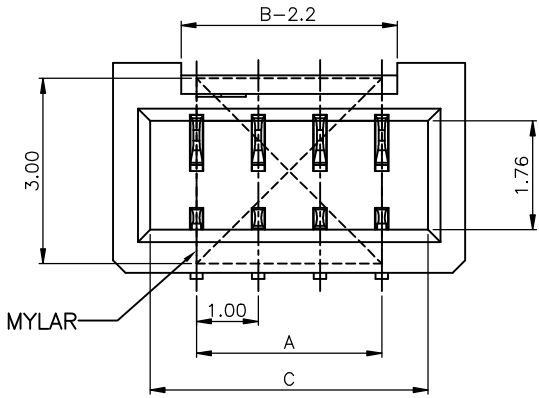


RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05



- NOTES:
- MATERIAL:
 - HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR:NATURAL.
 - CONTACT: COPPER ALLOY
 - FITTING NAIL: COPPER ALLOY
 - FINISH:
 - CONTACT: 50~100u" NICKEL UNDERPLATING OVERALL. N:90~120u" MATT TIN PLATING ON SOLDER TAILS, C:15u" GOLD PLANTING ON CONTACT AREA, GOLD FLASH ON SOLDER AREA D:30u" GOLD PLANTING ON CONTACT AREA, GOLD FLASH ON SOLDER AREA S:15u" GOLD PLANTING ON CONTACT AREA, 1u" GOLD ON SOLDER AREA
 - FITTING NAIL: 50~100u" NICKEL UNDERPLATING OVERALL. N:90~120u" MATT TIN PLATING ON SOLDER TAILS,
 - REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
 - SPEC. PLS. REFER TO PS-50429-xxxx-xxx
 - PACKAGE PLS. REFER TO 50429-XXXX-TRP
 - PART NUMBER
- P/N LEGEND
- 50429-XXX X X-XXX
- NO OF CKT
 - PACKING
 - 0:TAPE & REEL
 - 4:TAPE & REEL WITH MYLAR
 - COLOR OF HOUSING
 - 001:NATURAL
 - PLATING
 - N:MATT TIN(LEAD FREE)
 - C:15u" GOLD ON CONTACT AREA
 - D:30u" GOLD PLANTING ON CONTACT AREA, GOLD FLASH ON SOLDER AREA
 - S:15u" GOLD PLANTING ON CONTACT AREA, 1u" GOLD ON SOLDER AREA

CKT	A	B	C	D
003	2.0	4.70	3.50	3.90
004	3.0	5.70	4.50	4.90
005	4.0	6.70	5.50	5.90
006	5.0	7.70	6.50	6.90
007	6.0	8.70	7.50	7.90
008	7.0	9.70	8.50	8.90
012	11.0	13.70	12.50	12.90
013	12.0	14.70	13.50	13.90
014	13.0	15.70	14.50	14.90
016	15.0	17.70	16.50	16.90

QUALITY SYMBOLS MAJOR Ⓢ CRITICAL Ⓢ GENERAL TOLERANCES (UNLESS SPECIFIED) X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	DRAWN BY	DATE	
	Sun,Ya Jie	22/12/05	
	CHECKED BY	DATE	
	Xu,Zhi Yong	22/12/05	
APPROVED BY		DATE	TITLE
Xu,Zhi Yong		22/12/05	1.0mm WTB CONN. SMT S/T S/R TYPE
UNITS		SIZE	RFQ NO.
mm	A4	A4	N/A
SCALE	SHEET NO.	REV	DWG NO.
1 : 1	1 OF 1	H	50429-XXXXX-XXX